

Jun-Fa Mao

List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

226
papers

2,552
citations

25
h-index

43
g-index

360
ext. papers

3,466
ext. citations

2.8
avg, IF

5.46
L-index

#	Paper	IF	Citations
226	Design of Compact Grid Array Antennas Using Gradient Slow-Wave Structures. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2022 , 1-1	3.8	0
225	A Portable 5.8 GHz Dual Circularly Polarized Interferometric Radar Sensor for Short-Range Motion Sensing. <i>IEEE Transactions on Antennas and Propagation</i> , 2022 , 1-1	4.9	2
224	Mitigation of Leakage and Stationary Clutters in Short-Range FMCW Radar With Hybrid Analog and Digital Compensation Technique. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2022 , 70, 62-73 ^{4.1}	4.1	2
223	Conductive Bridging-Based Memristive RF Switches on a Silicon Substrate. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2022 , 70, 24-34	4.1	
222	An Unconditionally Stable 2-D Stochastic WLP-FDTD Method for Geometric Uncertainty in Superconducting Transmission Lines. <i>IEEE Transactions on Applied Superconductivity</i> , 2022 , 32, 1-9	1.8	0
221	PhysioChair: A Dual-Frequency Radar System for Noninvasive and Continuous Detection of Physiological Signatures. <i>IEEE Sensors Journal</i> , 2022 , 1-1	4	1
220	Analytical Thermal Model for AlGaIn/GaN HEMTs Using Conformal Mapping Method. <i>IEEE Transactions on Electron Devices</i> , 2022 , 1-6	2.9	1
219	Contactless Measurement of Human Systolic Time Intervals Based on Doppler Cardiograms in Clinical Environment. <i>IEEE Microwave and Wireless Components Letters</i> , 2022 , 1-4	2.6	1
218	Theoretical and Experimental Investigations on Differential Aperture-Coupled Rectangular Laminated Resonator Antenna. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2022 , 1-1	3.8	1
217	DC-Independent High-Linear Motion Sensing Based on a Novel ACAA Algorithm. <i>IEEE Microwave and Wireless Components Letters</i> , 2022 , 32, 261-264	2.6	1
216	Theory and Analysis on Radiation Characteristics of Differential Rectangular Laminated Resonator Antenna. <i>IEEE Transactions on Antennas and Propagation</i> , 2022 , 1-1	4.9	1
215	Average Power Handling Capability of Microstrip Lines Considering Heat Convection and Self-Heating Effects with Temperature-Dependent Resistivity. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2022 , 1-1	1.7	
214	Interferometric Motion Sensing With a Single-Channel Radar Sensor Based on a Novel Calibration-Free Phase Demodulation Technique. <i>IEEE Microwave and Wireless Components Letters</i> , 2022 , 1-4	2.6	1
213	Two-Material-Filled Ridge Half-Mode Substrate Integrated Waveguide for Monomode Bandwidth Enhancement. <i>IEEE Microwave and Wireless Components Letters</i> , 2022 , 1-4	2.6	
212	A High-Isolation Duplexer With Mismatched Load Impedance for Integrated Sensing and Communication. <i>IEEE Microwave and Wireless Components Letters</i> , 2022 , 1-4	2.6	
211	4-D Gesture Sensing Using Reconfigurable Virtual Array Based on a 60-GHz FMCW MIMO Radar Sensor. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2022 , 1-1	4.1	3
210	An Ultrawideband Magnetic Probe With High Electric Field Suppression Ratio. <i>IEEE Transactions on Instrumentation and Measurement</i> , 2021 , 70, 1-9	5.2	4

209	Phase Correction in Asynchronous FMCW Radar Systems for Accurate Noncontact Cardiopulmonary Monitoring 2021 ,		1
208	A 4D Gesture Sensing Technique based on Spatiotemporal Detection with a 60 GHz FMCW MIMO Radar 2021 ,		1
207	Deep Sub-Wavelength Millimeter-Wave Radar Interferometry with a Novel Ego-Motion based Calibration Technique 2021 ,		3
206	Accurate Measurement of Human Vital Signs with Linear FMCW Radars under Proximity Stationary Clutters. <i>IEEE Transactions on Biomedical Circuits and Systems</i> , 2021 , PP,	5.1	5
205	Loop-Star Functions Including Multibranch Raw-Wilton-Glisson Basis Functions. <i>IEEE Transactions on Antennas and Propagation</i> , 2021 , 1-1	4.9	2
204	Millimeter-Wave Active Integrated Semielliptic CPW Slot Antenna With Ultrawideband Compensation of Ball Grid Array Interconnection. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2021 , 1-1	1.7	1
203	An Unequal Wilkinson Power Divider Based on Integrated Passive Device Technology and Parametric Model. <i>IEEE Microwave and Wireless Components Letters</i> , 2021 , 1-4	2.6	
202	DC IR-Drop Analysis of Power Distribution Networks by a Robin Transmission Condition Enhanced Discontinuous Galerkin Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2021 , 1-1	1.7	2
201	An Overview of Probe-Based Millimeter-Wave/Terahertz Far-Field Antenna Measurement Setups [Measurements Corner]. <i>IEEE Antennas and Propagation Magazine</i> , 2021 , 63, 63-118	1.7	6
200	A Slow Wave Ridged Half-Mode Substrate Integrated Waveguide With Spoof Surface Plasmon Polaritons. <i>IEEE Transactions on Plasma Science</i> , 2021 , 49, 1818-1825	1.3	6
199	Ridged Substrate Integrated Coaxial Line for Wideband Millimeter-Wave Transmission. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2021 , 69, 2981-2988	4.1	2
198	Efficient transient thermal simulation with Laguerre-based finite-element method and domain decomposition. <i>Numerical Heat Transfer, Part B: Fundamentals</i> , 2021 , 80, 14-28	1.3	0
197	A Wideband Differentially Fed Dual-Polarized Laminated Resonator Antenna. <i>IEEE Transactions on Antennas and Propagation</i> , 2021 , 69, 4148-4153	4.9	6
196	Miniaturized Half-Mode T-Septum SIW Bandpass Filter With an Ultrawide Stopband. <i>IEEE Microwave and Wireless Components Letters</i> , 2021 , 31, 853-856	2.6	3
195	A 24 GHz Microstrip Comb Array Antenna With High Sidelobe Suppression for Radar Sensor. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2021 , 20, 1220-1224	3.8	2
194	A Fast Semi-Analytic Approach for Combined Electromigration and Thermomigration Analysis for General Multisegment Interconnects. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , 2021 , 40, 350-363	2.5	1
193	A quantification control method of electromagnetic environmental effects for complex systems. <i>Journal of Electromagnetic Waves and Applications</i> , 2021 , 35, 245-261	1.3	
192	Vivaldi Antenna Array with Heat Dissipation Enhancement for Millimeter-Wave Applications. <i>IEEE Transactions on Antennas and Propagation</i> , 2021 , 1-1	4.9	1

191	Multibranch Rao-Wilton-Glisson Basis Functions for Electromagnetic Scattering Problems. <i>IEEE Transactions on Antennas and Propagation</i> , 2021 , 1-1	4.9	5
190	A Flat Passband Predistorted Bandpass Filter with Folded Substrate Integrated Waveguide. <i>IEEE Transactions on Circuits and Systems II: Express Briefs</i> , 2021 , 1-1	3.5	4
189	Miniaturization of Frequency-Reconfigurable Antenna Using Periodic Slow-Wave Structure. <i>IEEE Transactions on Antennas and Propagation</i> , 2021 , 1-1	4.9	4
188	A New Gysel Out-of-Phase Power Divider With Arbitrary Power Dividing Ratio Based on Analysis Method of Equivalence of N-Port Networks. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2021 , 69, 1335-1343	4.1	0
187	. <i>IEEE Transactions on Antennas and Propagation</i> , 2021 , 69, 4681-4687	4.9	1
186	Nonlinear Thermal Analysis of AlGaIn/GaN HEMTs With Temperature-Dependent Parameters. <i>IEEE Transactions on Electron Devices</i> , 2021 , 68, 4565-4570	2.9	0
185	Pattern-Steerable Endfire Plasma Array Antenna. <i>IEEE Transactions on Antennas and Propagation</i> , 2021 , 1-1	4.9	2
184	Protection Effects Using Transient Voltage Suppressor Diodes Based Circuits Under High-Power Microwave Pulses. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2021 , 1-7	2	
183	Low-Loss Heterogeneous Integrations With High Output Power Radar Applications at W-Band. <i>IEEE Journal of Solid-State Circuits</i> , 2021 , 1-1	5.5	4
182	Large Displacement Motion Interferometry With Modified Differentiate and Cross-Multiply Technique. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2021 , 1-1	4.1	10
181	Noncontact High-Linear Motion Sensing Based on A Modified Differentiate and Cross-Multiply Algorithm 2020 ,		8
180	A Novel Design of Compact Out-of-Phase Power Divider With Arbitrary Ratio. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2020 , 68, 5235-5243	4.1	2
179	Analysis on a 77 GHz MIMO Radar for Touchless Gesture Sensing 2020 , 1-1		6
178	Half-Mode Substrate Integrated Waveguide Dispersion Tailoring Using 2.5-D Spoof Surface Plasmon Polaritons Structure. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2020 , 68, 2539-2550	4.1	13
177	Compact Fractional-Order Model of On-Chip Inductors With BCB on High Resistivity Silicon. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 878-886	1.7	4
176	Heatsink Antenna Array for Millimeter-Wave Applications. <i>IEEE Transactions on Antennas and Propagation</i> , 2020 , 68, 7664-7669	4.9	8
175	Low-Profile Broadband Plasma Antenna for Naval Communications in VHF and UHF Bands. <i>IEEE Transactions on Antennas and Propagation</i> , 2020 , 68, 4271-4282	4.9	9
174	. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 1367-1374	1.7	5

173	Efficient Transient Thermal Simulation of ICs and Packages With Laguerre-Based Finite-Element Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 203-211	1.7	5
172	A Novel Automatically Designed EBG Structure by Improved GA for Ultrawideband SSN Mitigation of System in Package. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 123-133	1.7	6
171	A New Compact Power Divider Based on Capacitor Central Loaded Coupled Microstrip Line. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2020 , 68, 4249-4256	4.1	6
170	Microstrip Memristive Switch and Its Applications to RF Devices 2020 ,		1
169	Memristive Switch for Intelligent RF Applications 2020 ,		1
168	An Optimal Approach in Design of Microstrip-to- SIW Transition Using Bayesian Optimization 2020 ,		1
167	Fast Analytic Electromigration Analysis for General Multisegment Interconnect Wires. <i>IEEE Transactions on Very Large Scale Integration (VLSI) Systems</i> , 2020 , 28, 421-432	2.6	5
166	A novel numerical method for steady-state thermal simulation based on loop-tree and HBRWG basis functions. <i>Numerical Heat Transfer, Part B: Fundamentals</i> , 2020 , 78, 348-363	1.3	
165	A Compact 2-D Stochastic FDTD Method for Uncertainty Analysis in Superconducting Transmission Lines. <i>IEEE Transactions on Applied Superconductivity</i> , 2020 , 30, 1-7	1.8	1
164	Integrated multi-scheme digital modulations of spoof surface plasmon polaritons. <i>Science China Information Sciences</i> , 2020 , 63, 1	3.4	10
163	Transient Coanalysis of Multicoupled Passive Transmission Lines and Josephson Junctions Based on FDTD. <i>IEEE Transactions on Applied Superconductivity</i> , 2020 , 30, 1-7	1.8	0
162	A Wideband Microstrip-Fed Dielectric Resonator Antenna Array With Defected Ground Structure 2019 ,		1
161	Active Integrated Dielectric Resonator Antenna-in-Package Design. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2019 , 18, 2414-2418	3.8	3
160	An Electrically Steerable Parasitic Array Radiator in Package Based on Liquid Crystal. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2019 , 18, 2365-2369	3.8	6
159	Integration of \$\$\$ /Ka/ \$D\$ -Band Antennas in LTCC With a Cylindrical Radome for Triband Applications. <i>IEEE Transactions on Antennas and Propagation</i> , 2019 , 67, 5781-5789	4.9	3
158	An Overview of the Development of Antenna-in-Package Technology for Highly Integrated Wireless Devices. <i>Proceedings of the IEEE</i> , 2019 , 107, 2265-2280	14.3	49
157	A Single-Ended-to-Balanced Impedance-Transforming Branch-Line Coupler With Arbitrary Power Division Ratio. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2019 , 67, 949-956	4.1	10
156	A General Method for Balanced-to-Unbalanced Filtering Out-of-Phase Power Divider Design. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2019 , 67, 2693-2700	4.1	2

155	Fast Nested Cross Approximation Algorithm for Solving Large-Scale Electromagnetic Problems. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2019 , 67, 3271-3283	4.1	5
154	Modified FSIW Filter With π Transmission Zeros Using BCB-Based MEMS Technology. <i>IEEE Microwave and Wireless Components Letters</i> , 2019 , 29, 520-522	2.6	3
153	Quintuple-Mode W-Band Packaged Filter Based on a Modified Quarter-Mode Substrate-Integrated Waveguide Cavity. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019 , 9, 2237-2247	1.7	15
152	Transient Electromagnetic-Thermal Simulation of Dispersive Media Using DGTD Method. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2019 , 1-9	2	7
151	A Balanced-to-Balanced Rat-Race Coupling Network Based on Defected Slots. <i>IEEE Microwave and Wireless Components Letters</i> , 2019 , 29, 459-461	2.6	10
150	A Pair of Parallel Differential Magnetic-Field Probes with High Spatial Resolution and Wide Frequency Bandwidth 2019 ,		3
149	Design of Substrate Integrated Coaxial Line under Silicon-based MEMS Process 2019 ,		1
148	A SIW-fed Parasitic Cavity Resonator Antenna in LTCC Technology 2019 ,		2
147	Dualfunction Dielectric Resonator as Antenna and Phase-Delay-Line Load: Designs of Compact Circularly Polarized/Differential Antennas. <i>IEEE Transactions on Antennas and Propagation</i> , 2018 , 66, 414-419	4.9	25
146	On-chip intercalated-graphene inductors for next-generation radio frequency electronics. <i>Nature Electronics</i> , 2018 , 1, 46-51	28.4	45
145	Ruggedness Characterization of Bonding Wire Arrays in LD MOSFET-Based Power Amplifiers. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018 , 8, 1032-1041	1.7	3
144	Mixed-Mode Property of Defected Ground Structure and Its Application in Balanced Network Design With Harmonic Suppression. <i>IEEE Microwave and Wireless Components Letters</i> , 2018 , 28, 188-190	2.6	2
143	\mathcal{H} -Matrix Accelerated Contour Integral Method for Modeling Multiconductor Transmission Lines. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2018 , 60, 552-555	2	
142	High-Speed Interconnect System Using QPSK Scheme Based on Substrate Integrated Waveguide. <i>Journal of Circuits, Systems and Computers</i> , 2018 , 27, 1850014	0.9	3
141	Equivalent Surface Impedance-Based Mixed Potential Integral Equation Accelerated by Optimized \mathcal{H} -Matrix for 3-D Interconnects. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2018 , 66, 22-34	4.1	9
140	High-Frequency Electrothermal Characterization of TSV-Based Power Delivery Network. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018 , 8, 2171-2179	1.7	4
139	Electromagnetic-thermal simulation of Lorentz media by the DGTD method 2018 ,		1
138	Experiments and Comparisons of Power to Failure for SiGe-Based Low-Noise Amplifiers Under High-Power Microwave Pulses. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2018 , 60, 1427-1435	2	5

137	Substrate Integrated Waveguide Filter With Flat Passband Based on Complex Couplings. <i>IEEE Microwave and Wireless Components Letters</i> , 2018 , 28, 494-496	2.6	11
136	Microstrip-Fed Differential Dielectric Resonator Antenna and Array. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2018 , 17, 1736-1739	3.8	17
135	A Compact 2-D WLP-FDTD Method for Superconducting Microstrip Lines 2018 ,		3
134	Transient Electro-Thermal Analysis of On-Chip Interconnects in the Presence of ESD Pulses Using DGTD Method 2018 ,		1
133	Design of a Novel Quarter-Mode Substrate-Integrated Waveguide Filter With Multiple Transmission Zeros and Higher ModeSuppressions. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2018 , 66, 5573-5584	4.1	14
132	A Semianalytical Gradient Model for Characterization of Conductors With Surface Roughness. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2018 , 66, 5391-5398	4.1	2
131	Theoretical and Experimental Investigation of HMSIW-Based High-Speed Data Transmission System Using QPSK Scheme. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018 , 8, 1938-1947	1.7	2
130	Dual-sleeve wideband monopole antenna for shipborne systems in VHF band. <i>Electronics Letters</i> , 2018 , 54, 1102-1104	1.1	4
129	An Analytical Gradient Model for the Characterization of Conductor Surface Roughness Effects 2018 ,		4
128	High Modes Suppressions with Transmission Zeros Design for a Novel Quarter-mode SIW Filter 2018 ,		3
127	Wafer level heterogeneous integration of a millimeter-wave transceiver module and its EMC problems 2018 ,		1
126	A Wideband Filtering Balanced-to-Unbalanced Out-of-Phase Power Divider. <i>IEEE Microwave and Wireless Components Letters</i> , 2018 , 28, 870-872	2.6	8
125	Time-Domain Analysis of Noise Coupling Between Package and PCB Power/Ground Planes Based on WLP-FDTD. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2017 , 7, 269-275	1.7	2
124	Novel Surface Impedance Modeling for Broadband Parameter Extraction of 3-D Interconnects. <i>IEEE Microwave and Wireless Components Letters</i> , 2017 , 27, 7-9	2.6	7
123	Transient Thermal Analysis of 3-D Integrated Circuits Packages by the DGTD Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2017 , 7, 862-871	1.7	16
122	High-Frequency Analysis of Intercalated Multilayer Graphene (IMLG) and Implication for Tunable Terahertz Resonator Design. <i>IEEE Access</i> , 2017 , 5, 7532-7541	3.5	2
121	A Wideband Millimeter-Wave Substrate Integrated Coaxial Line Array for High-Speed Data Transmission. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2017 , 65, 2789-2800	4.1	20
120	A Bandpass Graphene Frequency Selective Surface With Tunable Polarization Rotation for THz Applications. <i>IEEE Transactions on Antennas and Propagation</i> , 2017 , 65, 662-672	4.9	44

119	Hybrid cross approximation for electric field integral equation based scattering analysis 2017 ,		4
118	Stacked patch array in LTCC for 28 GHz antenna-in-package applications 2017 ,		6
117	Cavity Model Analysis of a Dual-Probe-Feed Circular Microstrip Patch Antenna. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2016 , 15, 44-47	3.8	6
116	FLAT-PASSBAND SUBSTRATE INTEGRATED WAVEGUIDE FILTER WITH RESISTIVE COUPLINGS. <i>Progress in Electromagnetics Research C</i> , 2016 , 62, 1-10	0.9	1
115	A Generalized Transition Matrix Model for Open-Ended Cavity With Complex Internal Structures. <i>IEEE Transactions on Antennas and Propagation</i> , 2016 , 64, 3920-3930	4.9	5
114	Lossy substrate integrated waveguide filter with flat passband 2016 ,		1
113	A Flat-Passband Microstrip Filter With Nonuniform- Q Dual-Mode Resonators. <i>IEEE Microwave and Wireless Components Letters</i> , 2016 , 26, 183-185	2.6	13
112	Diagnosis and tuning of filtering antenna based on extracted coupling matrix 2016 ,		4
111	Electrothermal Cosimulation of 3-D Carbon-Based Heterogeneous Interconnects. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2016 , 6, 518-526	1.7	19
110	A Four-Way Microstrip Filtering Power Divider With Frequency-Dependent Couplings. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2015 , 63, 3494-3504	4.1	62
109	A wide band millimeter-wave substrate integrated coaxial line (SICL) for high speed data transmission 2015 ,		8
108	Fast transient electro-thermal simulation of on-chip interconnects in the presence of ESD pulses 2015 ,		2
107	Modeling and Fast Simulation of Multiwalled Carbon Nanotube Interconnects. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2015 , 57, 232-240	2	28
106	A new quad-band Wilkinson power divider. <i>Journal of Electromagnetic Waves and Applications</i> , 2014 , 28, 1622-1634	1.3	5
105	Signal-Integrity Optimization for Complicated Multiple-Input Multiple-Output Networks Based on Data Mining of S-Parameters. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2014 , 4, 1184-1192	1.7	4
104	Analyzing Electromagnetic Systems on Electrically Large Platform Using a GTM-PO Hybrid Method with Synthetic Basis Functions. <i>International Journal of Antennas and Propagation</i> , 2014 , 2014, 1-7	1.2	
103	2014 ,		3
102	High-speed data transmission system using half mode substrate integrated waveguide 2014 ,		3

101	Immunity Analysis and Experimental Investigation of a Low-Noise Amplifier Using a Transient Voltage Suppressor Diode Under Direct Current Injection of HPM Pulses. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2014 , 56, 1715-1718	2	10
100	Compact Tunable Bandpass Filter With a Fixed Out-of-Band Rejection Based on Hilbert Fractals. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2013 , 3, 391-400	1.7	8
99	A Balanced-to-Balanced Power Divider With Arbitrary Power Division. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2013 , 61, 2831-2840	4.1	69
98	Collaborative Design of a New Dual-Bandpass 180° Hybrid Coupler. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2013 , 61, 1053-1066	4.1	26
97	New Power Distribution Network Design Method for Digital Systems Using Time-Domain Transient Impedance. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2013 , 3, 1399-1408	1.7	3
96	A Systematic Electromagnetic-Circuit Method for EMI Analysis of Coupled Interconnects on Dispersive Dielectrics. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2013 , 61, 1-13	4.1	47
95	A Novel Compact Dual-Band Antenna Array With High Isolations Realized Using the Neutralization Technique. <i>IEEE Transactions on Antennas and Propagation</i> , 2013 , 61, 1956-1962	4.9	17
94	Overlapped optics induced perfect coherent effects. <i>Scientific Reports</i> , 2013 , 3, 3569	4.9	13
93	Miniaturization of Rat-Race Coupler With Dual-Band Arbitrary Power Divisions Based on Stepped-Impedance Double-Sided Parallel-Strip Line. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2012 , 2, 2017-2030	1.7	21
92	Miniaturized Tapered EBG Structure With Wide Stopband and Flat Passband. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2012 , 11, 314-317	3.8	21
91	A New Balanced-to-Balanced Power Divider/Combiner. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2012 , 60, 2791-2798	4.1	86
90	Embedded Planar EBG and Shorting Via Arrays for SSN Suppression in Multilayer PCBs. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2012 , 11, 1430-1433	3.8	10
89	Worst Case Power Noise Estimation and Compensation Design for Zero Coupling with Multiple Switching I/Os. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2012 , 54, 1105-1111	2	1
88	A Note on the Construction of Synthetic Basis Functions for Antenna Arrays. <i>IEEE Transactions on Antennas and Propagation</i> , 2012 , 60, 3509-3512	4.9	5
87	Notched ultra-wideband (UWB) bandpass filter with wide upper stopband based on electromagnetic bandgap (EBG) structures 2012 ,		2
86	Investigation on dual-armed sinuous antenna 2012 ,		3
85	Design of a Beam Reconfigurable THz Antenna With Graphene-Based Switchable High-Impedance Surface. <i>IEEE Nanotechnology Magazine</i> , 2012 , 11, 836-842	2.6	79
84	Compact quasi-elliptic bandpass filter based on folded ridge substrate integrated waveguide (FRSIW) 2012 ,		6

83	An efficient intra-frame rate control algorithm for H.264/AVC video coding. <i>Wuhan University Journal of Natural Sciences</i> , 2012 , 17, 243-248	0.4	1
82	A Half-Mode Substrate Integrated Waveguide Ring for Two-Way Power Division of Balanced Circuit. <i>IEEE Microwave and Wireless Components Letters</i> , 2012 , 22, 333-335	2.6	53
81	Transient thermal analysis of global interconnects based on transmission lines 2012 ,		1
80	Electrothermal coupling analysis of CMOS gates driving interconnects 2012 ,		1
79	Study on equivalent single conductor model of multi-walled carbon nanotube interconnects 2012 ,		3
78	Experimental demonstration of the wave squeezing effect based on inductor-capacitor networks. <i>Applied Physics Letters</i> , 2012 , 101, 074104	3.4	2
77	Analysis and Optimization of Thermal-Driven Global Interconnects in Nanometer Design. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2011 , 1, 1564-1572	1.7	4
76	Transient Analysis of CMOS-Gate-Driven π RLGC π Interconnects Based on FDTD. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , 2011 , 30, 574-583	2.5	43
75	. <i>IEEE Transactions on Electron Devices</i> , 2011 , 58, 2689-2701	2.9	25
74	Thermal runaway prediction based on electrothermal models in nanotechnologies 2011 ,		2
73	Equivalence Principle for Analyzing Steady-State Heat Conduction Problems. <i>Numerical Heat Transfer, Part B: Fundamentals</i> , 2011 , 59, 226-244	1.3	2
72	Performance enhancement research for printed circuit board manufacture in China 2011 ,		1
71	Mushroom-Type Ground Plane Structure for Wideband SSN Suppression in High-Speed Circuits. <i>IEEE Microwave and Wireless Components Letters</i> , 2011 , 21, 646-648	2.6	9
70	A bandstop filter based on non-bianisotropic complementary split ring resonators (NBCSRRs) 2011 ,		1
69	Design of a switchable high impedance surface based on single-layer doped graphene for THz application 2011 ,		3
68	A Compact Single/Dual-Polarized Broadband Antenna With SUM and Difference Beam Capabilities. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2010 , 9, 990-993	3.8	9
67	A 0.5–1 GHz CMOS Low Noise Amplifier Using Dual-Channel Shunt Technique. <i>IEEE Microwave and Wireless Components Letters</i> , 2010 , 20, 280-282	2.6	14
66	Compact Lowpass Filters With Sharp and Expanded Stopband Using Stepped Impedance Hairpin Units. <i>IEEE Microwave and Wireless Components Letters</i> , 2010 , 20, 310-312	2.6	56

65	A New Power-Ground Plane Modeling Method With Rectangle and Triangle Segmentation. <i>IEEE Transactions on Advanced Packaging</i> , 2010 , 33, 639-646		2
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